

PRACTICE QUESTIONS

NVIDIA

NCP-ARI

NVIDIA-Certified Professional: AI Rack and Interconnect

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EDITION Free Set 1

QUESTIONS 10

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EXAM NVIDIA NCP-ARI, NVIDIA-Certified Professional: AI Rack and Interconnect

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10 practice questions for the NVIDIA NCP-ARI exam, NVIDIA-Certified Professional: AI Rack and Interconnect, each followed by its answer and a short explanation. More free sets and the full practice exam: aiexamcerts.com/nvidia/ncp-ari. Spotted a mistake? Email support@aiexamcerts.com with the exam code NCP-ARI and the question number.

1. What is the main purpose of rPDU load balancing in an AC rack?

- A To increase the speed of the Ethernet links
- B To lower the GPU memory clock speed so that the rack draws less power from the room
- C To keep the current on each phase even so that no single circuit is overloaded
- D To remove the need for any grounding conductor

Answer: C

Balanced phases share the load so that no circuit reaches its limit before the others, which keeps the rack inside its electrical design. Link speed, memory clocks and grounding are unrelated to phase balance.

2. The cooling arrangement in which cool air enters through the front of the rack and warm air leaves at the rear is called a _____ aisle layout.

Answer: cold-aisle (also accepted: cold aisle)

A cold-aisle layout delivers cool air to the front intakes, and it is paired with a hot aisle at the back that collects the exhaust. Hot aisle is the tempting term because it is the return side of the same arrangement.

3. Which fact about rack airflow is most important when planning an AI row?

- A Airflow matters only for storage racks and not for GPU servers
- B Cables should block the front intake to keep dust out of the intake filters and fans
- C Hot air should be pushed under the raised floor into the intake tiles
- D Blanking panels and containment stop hot exhaust from re-entering the intakes

Answer: D

Blanking panels and containment keep warm exhaust from recirculating into intakes, which keeps inlet temperatures within specification. Blocking intakes with cables or recirculating exhaust through floor tiles creates the hot spots the question is about.

4. Which step should come first when verifying the grounding of a new AI rack?
- A Testing that the rack frame and PDU ground have a continuous bonding path to the building ground
 - B Installing the GPU drivers on each server before the rack is energized, bonded and tested for grounding
 - C Configuring the Ethernet leaf switch VLANs
 - D Labeling the fiber patch panel ports

Answer: A

Continuity of the bonding path to ground must be confirmed before the rack is energized, because a broken ground can leave metal parts at a dangerous potential. Driver installation and switch configuration come later and do not affect electrical safety.

5. Grounding can be verified by checking the continuity of the bonding path before a rack is energized.
- A True
 - B False

Answer: A (True)

A continuity test confirms that the rack's ground path is intact before power is applied, which is the standard pre-energization check. Testing with the equipment running would be unsafe and does not replace the continuity measurement.

6. Which cooling design takes heat from the rack through a closed secondary loop to a heat exchanger?
- A Open-window ventilation with no fans and no filters in the outside air path
 - B Liquid cooling with a CDU and a facility water loop
 - C A single fan mounted on the cable tray
 - D Evaporative cooling with a wet cardboard barrier

Answer: B

Liquid cooling moves heat through a closed rack loop and a CDU into the facility water loop, which carries it to heat rejection equipment. Passive ventilation and fans on cable trays do not carry heat through a closed loop, so they are weaker distractors.

7. Which two checks confirm that a data center row can support an AI deployment? (Choose two.)
- A The operating system version on the building management system
 - B Power capacity per PDU type compared with the planned rack loads
 - C Cooling capacity compared with the total heat the rack will reject
 - D The number of office chairs near the rack row
 - E The color of the cable jackets used in other rooms

Answer: B, C

Power and cooling capacity are the two resources that limit how much compute a row can host, so both must be checked against the planned load. Furniture, cable colors and building software are not capacity limits.

8. The power arrangement in which a second, fully independent set of feeds backs up every component is called _____ redundancy.

Answer: 2N (also accepted: 2N power, 2N feed, two-N)

2N redundancy gives every component two complete, independent power paths, so a whole feed can fail without loss of load. N+1 adds only one spare module, which is a weaker arrangement that the question is distinguishing from.

9. Which fact about rack power distribution is most accurate for AI systems?
- A PDU ratings are irrelevant once the rack is connected to a UPS
 - B A breaker can be run at its full rating continuously with no derating whenever the load is perfectly steady and the room is cool
 - C Rated loads of PDUs must be derated for continuous operation before the planned draw is compared with them
 - D PDUs only affect the network, not the power draw

Answer: C

Circuits and PDUs are derated for continuous loads, so the planned draw must stay under the derated limit rather than the nameplate. Assuming a breaker can carry its full rating continuously is the common error this option tests.

10. Which problem is most likely if an AI rack's exhaust temperature keeps rising even though the facility cooling is running?
- A A GPU driver version that is one minor release behind the version used in the lab
 - B A Slurm partition with too many nodes
 - C A fiber patch panel with dirty connectors
 - D Recirculated hot air from missing blanking panels or open gaps in the rack

Answer: D

Open gaps and missing blanking panels let exhaust air circle back to the intakes, which raises temperatures even when the cooling plant works. Software versions, scheduling and connector cleanliness do not change rack air temperature.